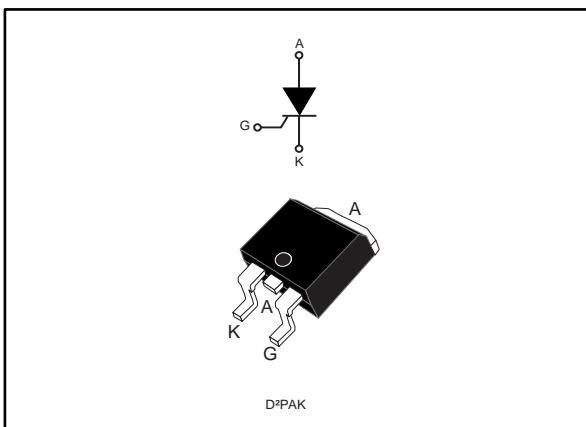


High temperature 40 A SCRs

Datasheet - production data



Features

- High junction temperature: $T_j = 150^\circ\text{C}$
- High noise immunity $dV/dt = 500 \text{ V}/\mu\text{s}$ up to 150°C
- Gate triggering current $I_{GT} = 15 \text{ mA}$
- Off-state voltage 600 V V_{DRM}/V_{RRM}
- High turn on current rise $dI/dt = 100 \text{ A}/\mu\text{s}$
- ECOPACK®2 compliant component

Applications

- Motorbike voltage regulator circuits
- Inrush current limiting circuit
- Motor control circuits and starters
- Solid state relays

Description

Thanks to its junction temperature T_j up to 150°C , the device offers high thermal performance operation up to 40 A. Its D²PAK package allows modern SMD designs as well as compact back to back configuration.

Its trade-off noise immunity ($dV/dt = 500 \text{ V}/\mu\text{s}$) versus its gate triggering current ($I_{GT} = 15 \text{ mA}$) and its turn-on current rise ($dI/dt = 100 \text{ A}/\mu\text{s}$) allow to design robust and compact control circuit for voltage regulator in motorbikes and industrial drives, overvoltage crowbar protection, motor control circuits in power tools and kitchen appliances, inrush current limiting circuits.

Table 1: Device summary

| Order code | Package | V_{DRM}/V_{RRM} | I_{GT} |
|------------|--------------------|-------------------|----------|
| TN4015H-6G | D ² PAK | 600 V | 15 mA |

1 Characteristics

Table 2: Absolute maximum ratings (limiting values), $T_j = 25^\circ\text{C}$ unless otherwise specified

| Symbol | Parameter | | Value | Unit | |
|---------------------|--|---------------------------|---------------------------|------------------------|------------------|
| $I_{T(\text{RMS})}$ | RMS on-state current (180 ° conduction angle) | $T_c = 119^\circ\text{C}$ | 40 | A | |
| $I_{T(\text{AV})}$ | Average on-state current (180 ° conduction angle) | $T_c = 120^\circ\text{C}$ | 25 | A | |
| | | $T_c = 125^\circ\text{C}$ | 22 | | |
| | | $T_c = 128^\circ\text{C}$ | 20 | | |
| I_{TSM} | Non repetitive surge peak on-state current | $t_p = 8.3 \text{ ms}$ | 394 | A | |
| | | $t_p = 10 \text{ ms}$ | 360 | | |
| I^2t | I^2t value for fusing | $t_p = 10 \text{ ms}$ | 648 | A^2s | |
| dI/dt | Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \leq 100 \text{ ns}$ | $f = 60 \text{ Hz}$ | 100 | $\text{A}/\mu\text{s}$ | |
| V_{DRM}/V_{RRM} | Repetitive peak off-state voltage | $T_j = 150^\circ\text{C}$ | 600 | V | |
| V_{DSM}/V_{RSM} | Non repetitive surge peak off-state voltage | $t_p = 10 \text{ ms}$ | $V_{DRM}/V_{RRM} + 100$ | V | |
| I_{GM} | Peak gate current | $t_p = 20 \mu\text{s}$ | $T_j = 150^\circ\text{C}$ | 4 | A |
| $P_{G(\text{AV})}$ | Average gate power dissipation | | $T_j = 150^\circ\text{C}$ | 1 | W |
| V_{RGM} | Maximum peak reverse gate voltage | | | 5 | V |
| T_{stg} | Storage junction temperature range | | | -40 to +150 | $^\circ\text{C}$ |
| T_j | Maximum operating junction temperature | | | -40 to +150 | $^\circ\text{C}$ |

Table 3: Electrical characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Test conditions | | Value | Unit | |
|----------|--|---------------------------|-------|------|------------------------|
| I_{GT} | $V_D = 12 \text{ V}$, $R_L = 33 \Omega$ | | Max. | 15 | mA |
| | | Max. | 1.3 | V | |
| V_{GD} | $V_D = V_{DRM}$, $R_L = 3.3 \text{ k}\Omega$ | $T_j = 150^\circ\text{C}$ | Min. | 0.15 | V |
| I_H | $I_T = 500 \text{ mA}$, gate open | | Max. | 60 | mA |
| I_L | $I_G = 1.2 \times I_{GT}$ | | Max. | 80 | mA |
| dV/dt | $V_D = 402 \text{ V}$, gate open | $T_j = 150^\circ\text{C}$ | Min. | 500 | $\text{V}/\mu\text{s}$ |
| t_{gt} | $I_{TM} = 80 \text{ A}$, $V_D = 402 \text{ V}$, $I_G = 30 \text{ mA}$, $(dI_G/dt)_{\text{max}} = 0.2 \text{ A}/\mu\text{s}$ | | Typ. | 1.9 | μs |
| t_q | $I_{TM} = 80 \text{ A}$, $V_D = 402 \text{ V}$, $(dI/dt)_{\text{off}} = 30 \text{ A}/\mu\text{s}$, $V_R = 25 \text{ V}$, $dV_D/dt = 50 \text{ V}/\mu\text{s}$ | $T_j = 150^\circ\text{C}$ | Typ. | 85 | μs |

Table 4: Static characteristics

| Symbol | Test conditions | | | Value | Unit |
|--------------------|---|---------------------------|------|-------|------------------|
| V_{TM} | $I_{TM} = 80 \text{ A}$, $t_p = 380 \mu\text{s}$ | $T_j = 25^\circ\text{C}$ | Max. | 1.6 | V |
| V_{TO} | Threshold voltage | $T_j = 150^\circ\text{C}$ | Max. | 0.85 | |
| R_D | Dynamic resistance | $T_j = 150^\circ\text{C}$ | Max. | 10 | $\text{m}\Omega$ |
| I_{DRM}, I_{RRM} | $V_D = V_{DRM} = V_{RRM}$ | $T_j = 25^\circ\text{C}$ | Max. | 10 | μA |
| | | $T_j = 150^\circ\text{C}$ | | 6 | mA |

Table 5: Thermal parameters

| Symbol | Parameter | | | Value | Unit |
|---------------|--------------------------|----------------------------|------|-------|------|
| $R_{th(j-c)}$ | Junction to case (DC) | $S^{(1)} = 1 \text{ cm}^2$ | Max. | 0.8 | °C/W |
| $R_{th(j-a)}$ | Junction to ambient (DC) | | Typ. | 45 | |

Notes:

(1)S = Copper surface under tab

1.1 Characteristics (curves)

Figure 1: Maximum average power dissipation versus average on-state current

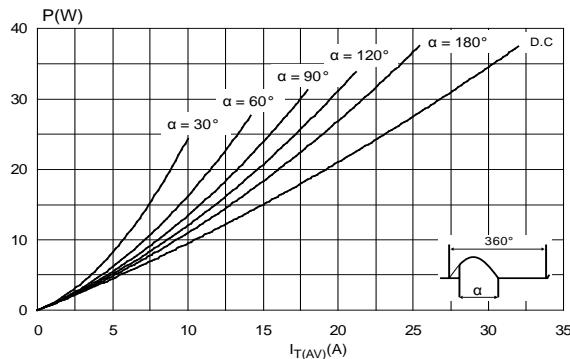


Figure 2: Average and DC on-state current versus case temperature

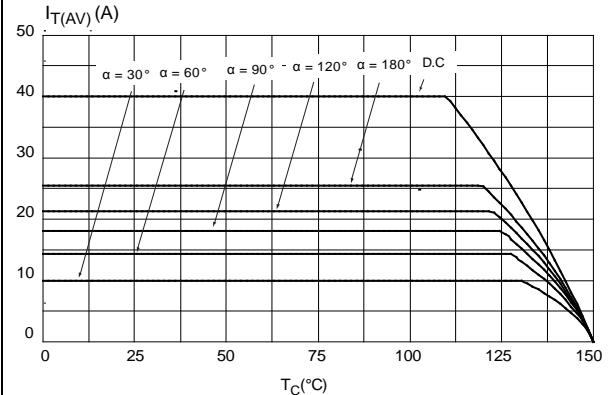


Figure 3: Average and D.C. on state current versus ambient temperature

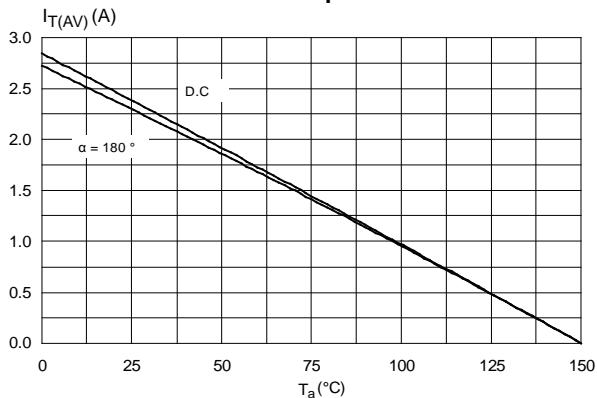


Figure 4: Relative variation of thermal impedance versus pulse duration

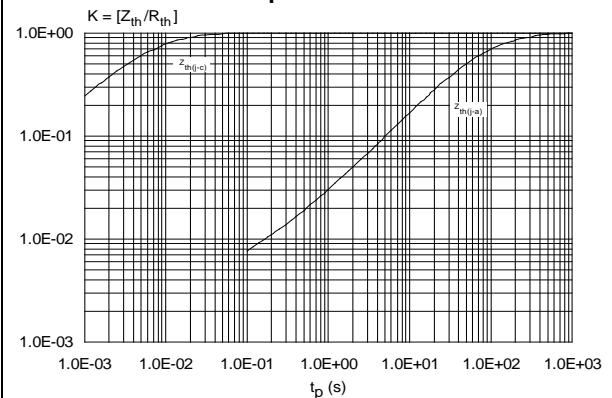


Figure 5: Relative variation of gate trigger current and gate voltage versus junction temperature (typical values)

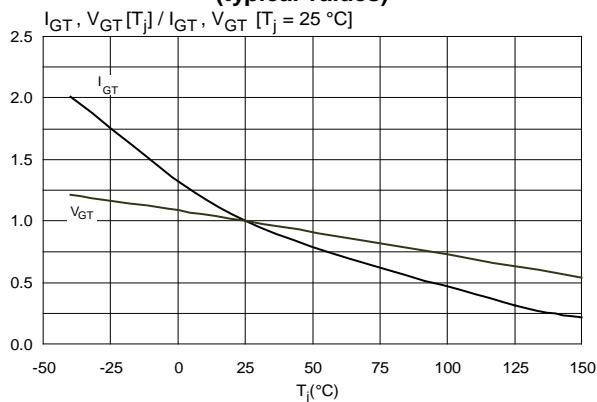
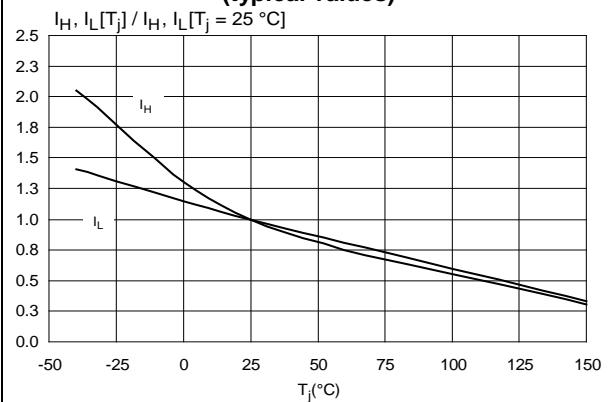


Figure 6: Relative variation of holding and latching current versus junction temperature (typical values)



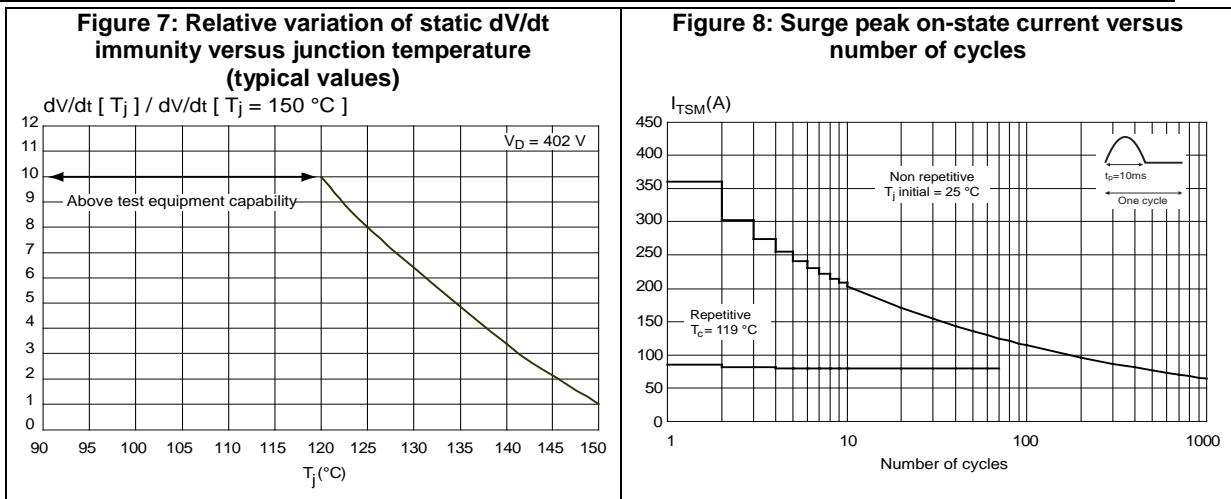


Figure 8: Surge peak on-state current versus number of cycles

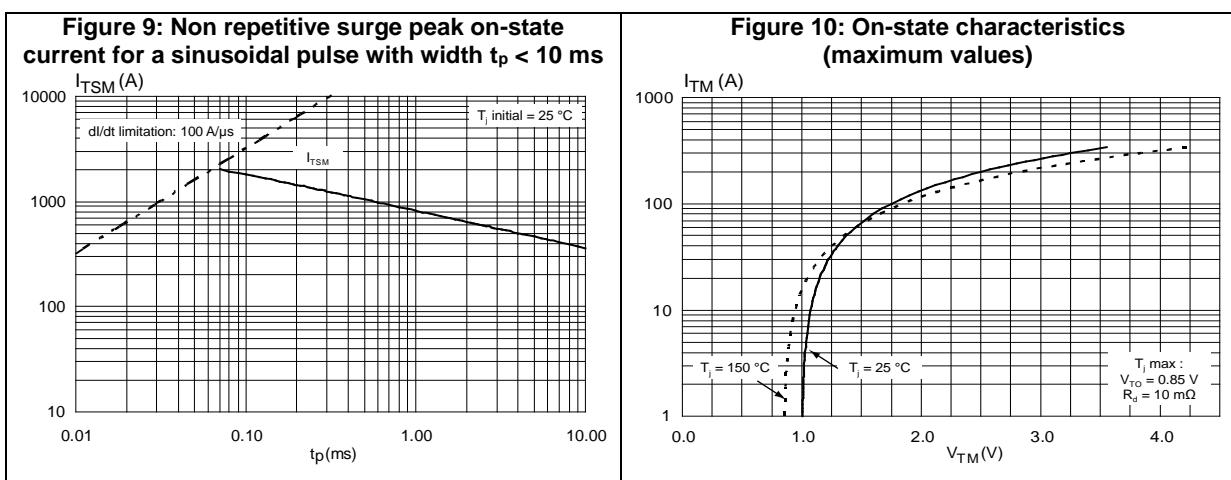
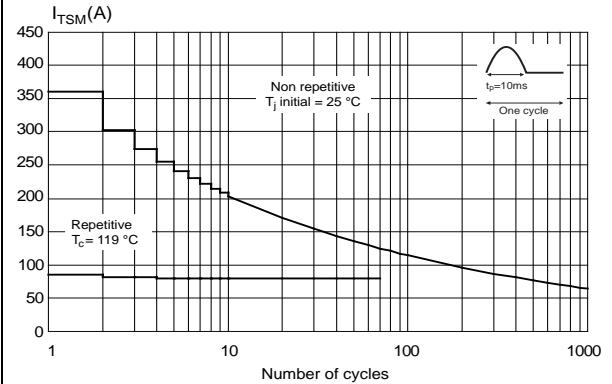


Figure 10: On-state characteristics (maximum values)

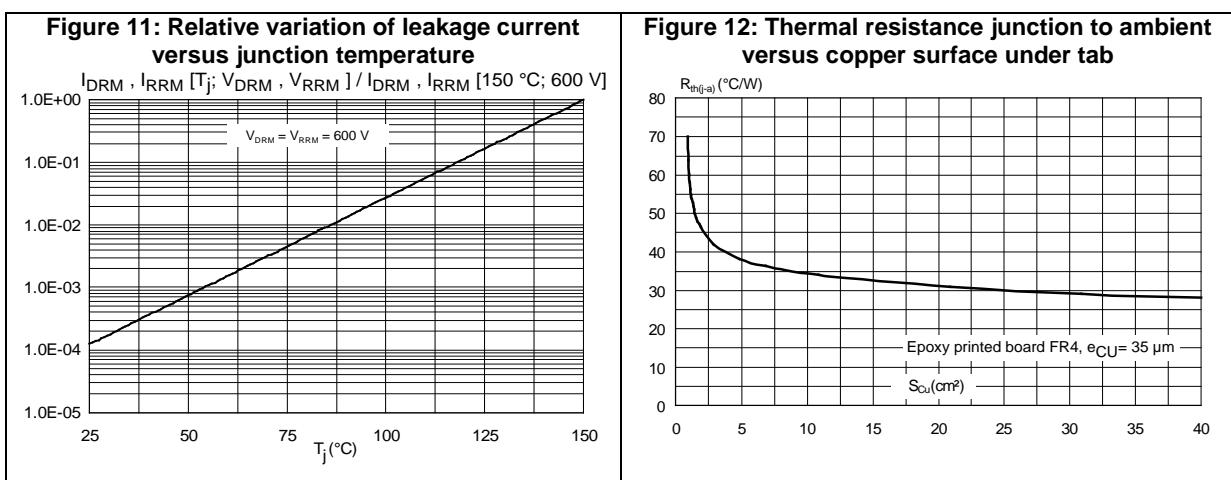
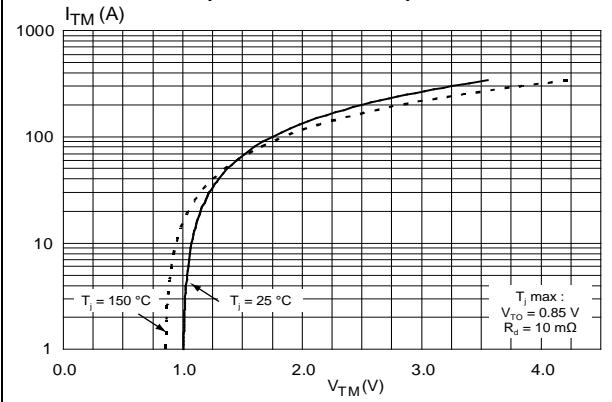
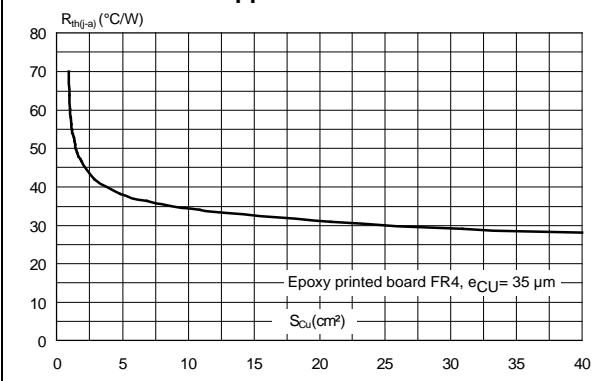


Figure 12: Thermal resistance junction to ambient versus copper surface under tab



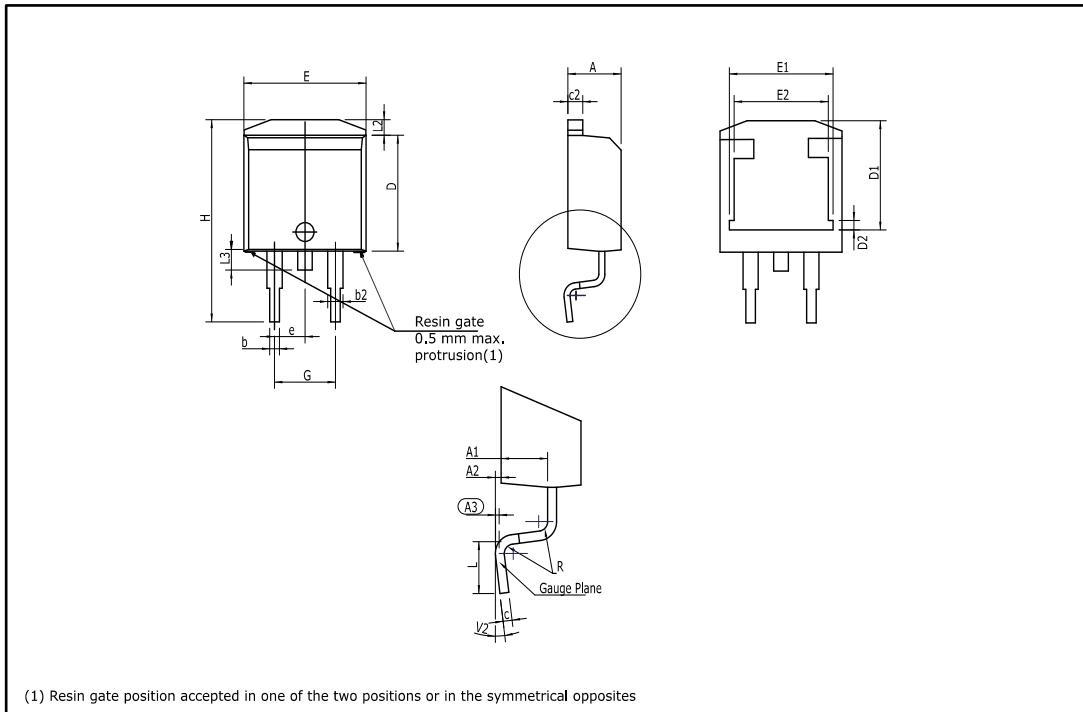
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Lead-free, halogen-free package

2.1 D²PAK package information

Figure 13: D²PAK package outline



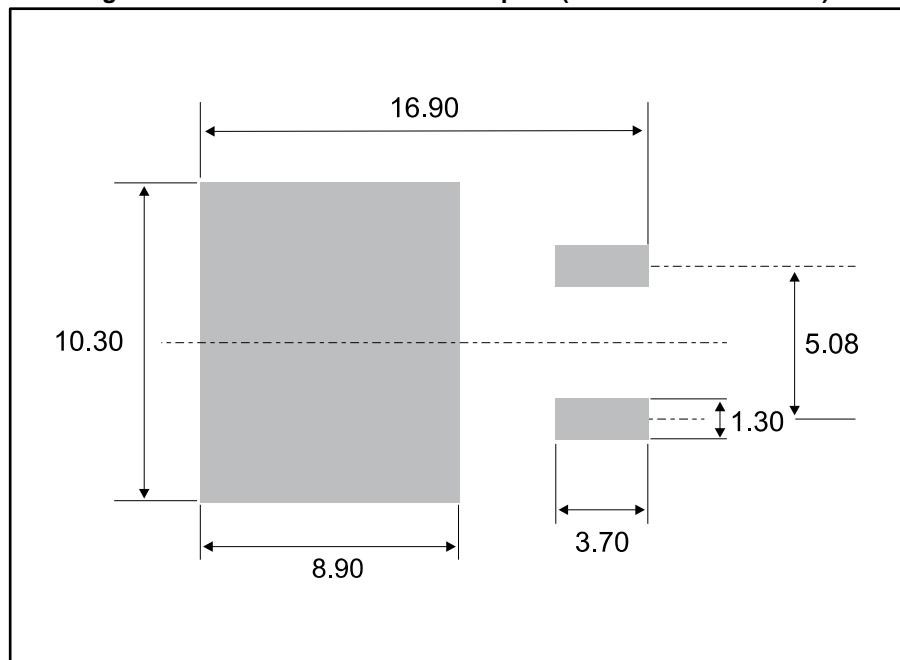
(1) Resin gate position accepted in one of the two positions or in the symmetrical opposites

Table 6: D²PAK package mechanical data

| Ref. | Dimensions | | | | | |
|------|-------------|------|-------|-----------------------|--------|--------|
| | Millimeters | | | Inches ⁽¹⁾ | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 4.30 | | 4.60 | 0.1693 | | 0.1811 |
| A1 | 2.49 | | 2.69 | 0.0980 | | 0.1059 |
| A2 | 0.03 | | 0.23 | 0.0012 | | 0.0091 |
| A3 | | 0.25 | | | 0.0098 | |
| b | 0.70 | | 0.93 | 0.0276 | | 0.0366 |
| b2 | 1.25 | | 1.7 | 0.0492 | | 0.0669 |
| c | 0.45 | | 0.60 | 0.0177 | | 0.0236 |
| c2 | 1.21 | | 1.36 | 0.0476 | | 0.0535 |
| D | 8.95 | | 9.35 | 0.3524 | | 0.3681 |
| D1 | 7.50 | | 8.00 | 0.2953 | | 0.3150 |
| D2 | 1.30 | | 1.70 | 0.0512 | | 0.0669 |
| e | 2.54 | | | 0.1 | | |
| E | 10.00 | | 10.28 | 0.3937 | | 0.4047 |
| E1 | 8.30 | | 8.70 | 0.3268 | | 0.3425 |
| E2 | 6.85 | | 7.25 | 0.2697 | | 0.2854 |
| G | 4.88 | | 5.28 | 0.1921 | | 0.2079 |
| H | 15 | | 15.85 | 0.5906 | | 0.6240 |
| L | 1.78 | | 2.28 | 0.0701 | | 0.0898 |
| L2 | 1.27 | | 1.40 | 0.0500 | | 0.0551 |
| L3 | 1.40 | | 1.75 | 0.0551 | | 0.0689 |
| R | | 0.40 | | | 0.0157 | |
| V2 | 0° | | 8° | 0° | | 8° |

Notes:

(1) Dimensions in inches are given for reference only

Figure 14: D²PAK recommended footprint (dimensions are in mm)

3 Ordering information

Figure 15: Ordering information scheme

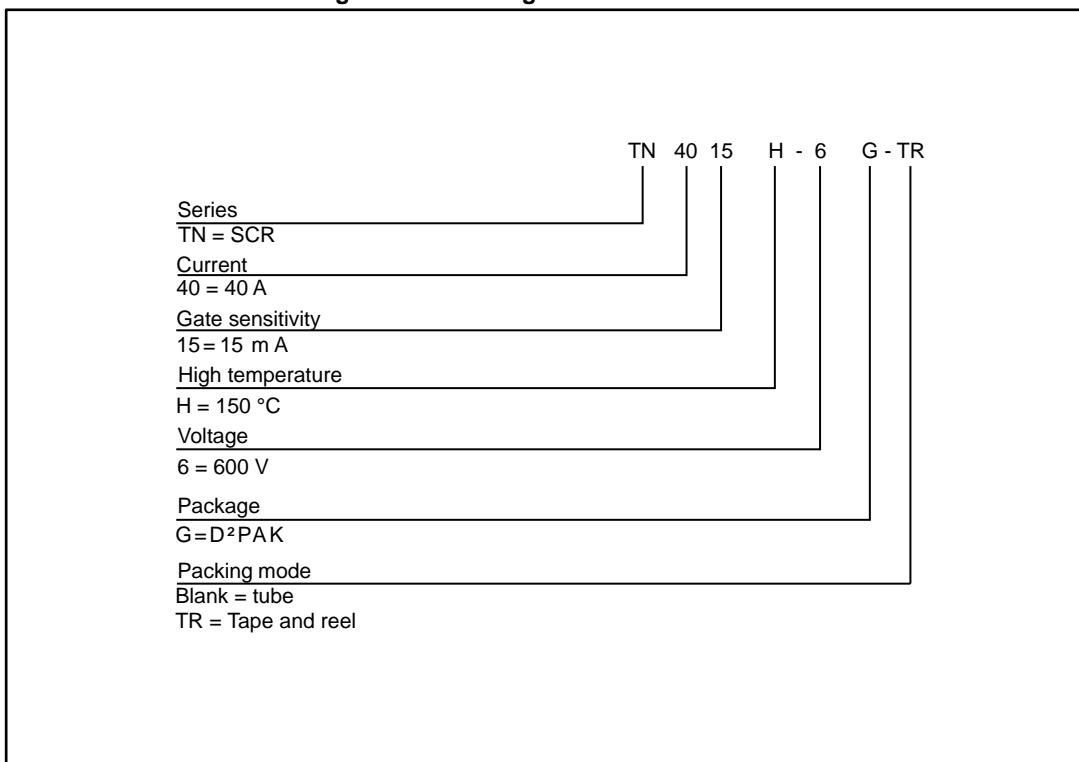


Table 7: Ordering information

| Order code | Marking | Package | Weight | Base qty. | Delivery mode |
|---------------|----------|--------------------|--------|-----------|---------------|
| TN4015H-6G | TN4015H6 | D ² PAK | 1.5 g | 50 | Tube |
| TN4015H-6G-TR | TN4015H6 | D ² PAK | 1.5 g | 1000 | Tape and reel |

4 Revision history

Table 8: Document revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 01-Aug-2016 | 1 | Initial release. |
| 22-May-2017 | 2 | Updated Figure 13: "D²PAK package outline" . |

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